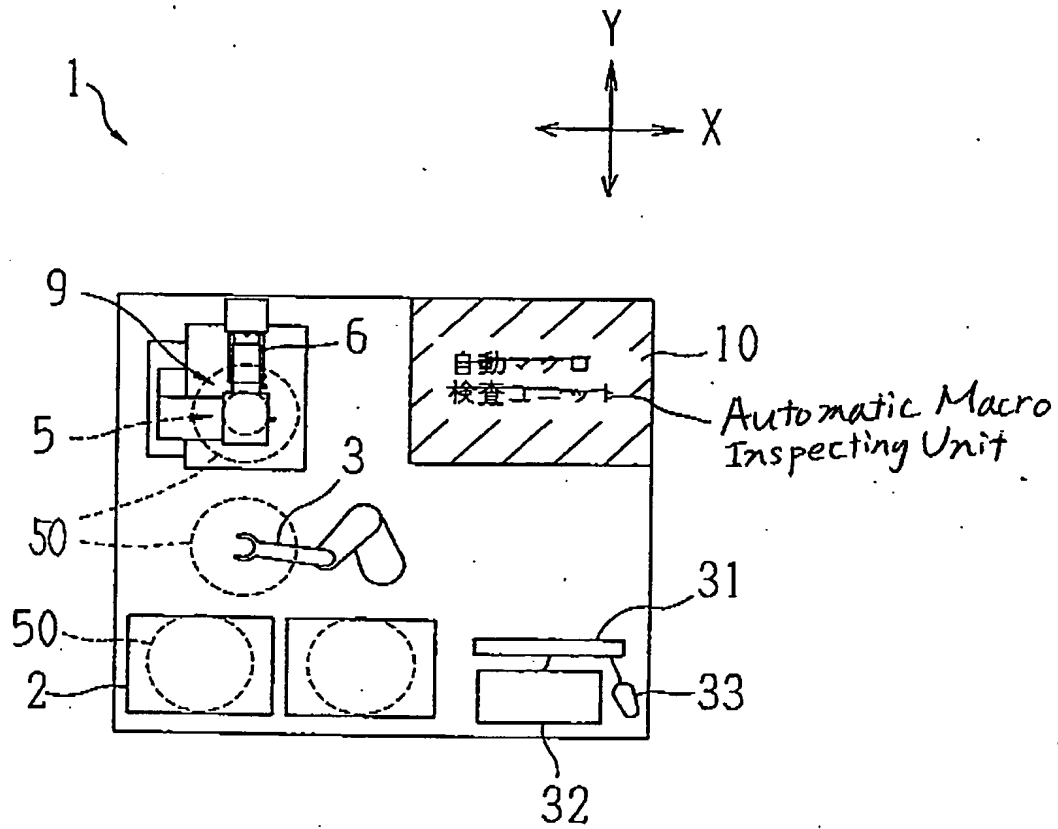


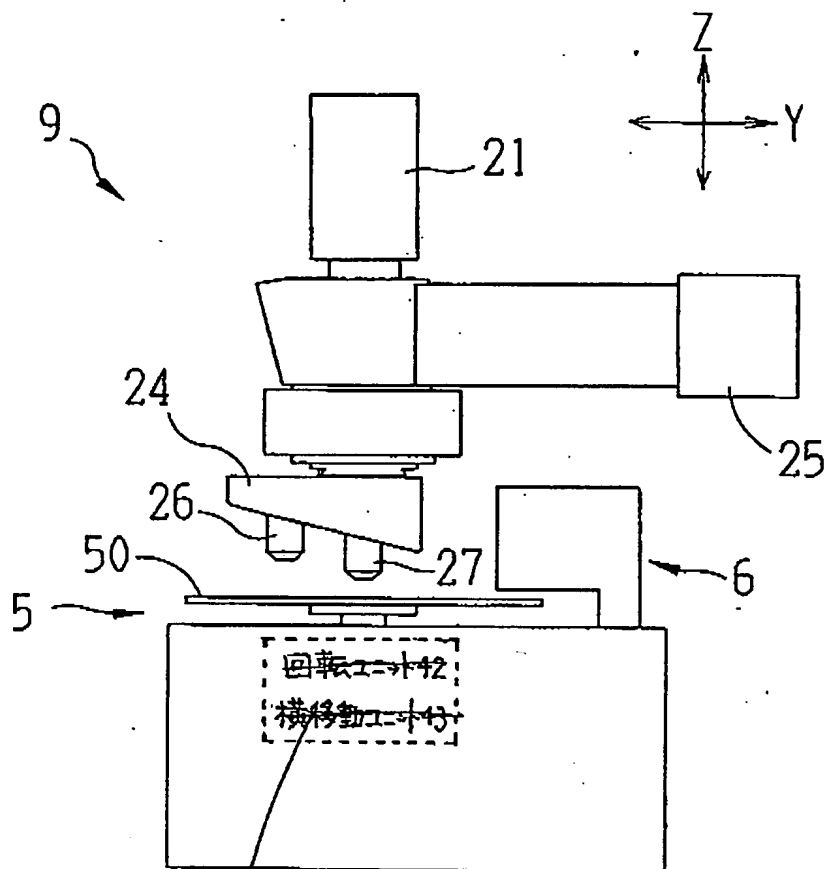
【書類名】 図面

【図1】 Fig.1



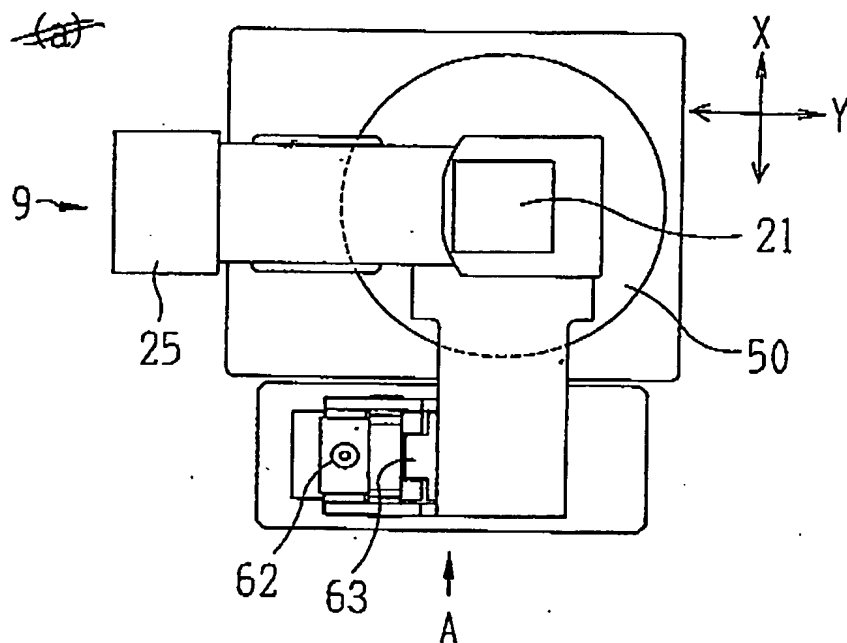
【圖2】

FIG. 2

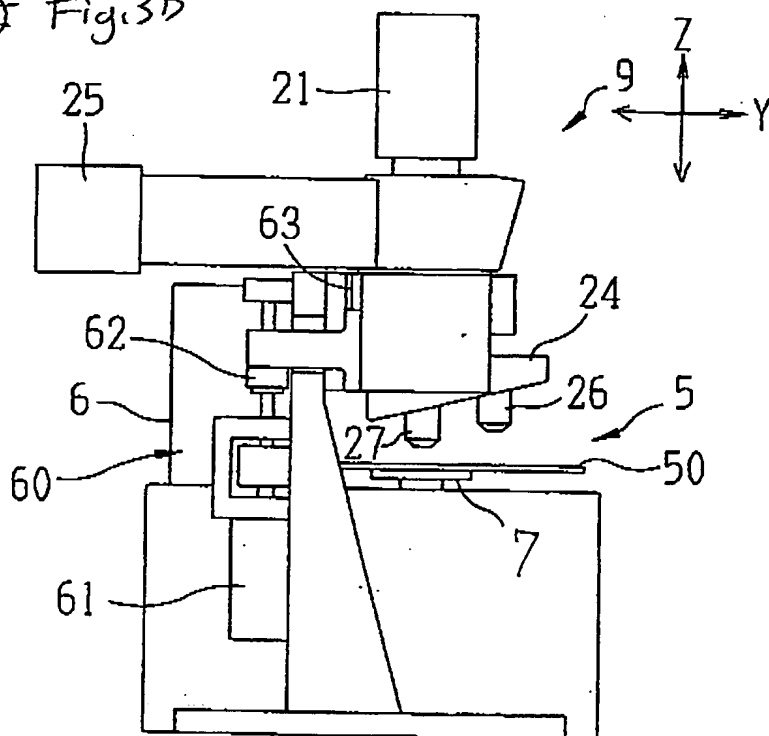


1 Rotating Unit 42
Horizontally - Moving Unit 43

図3A Fig.3A

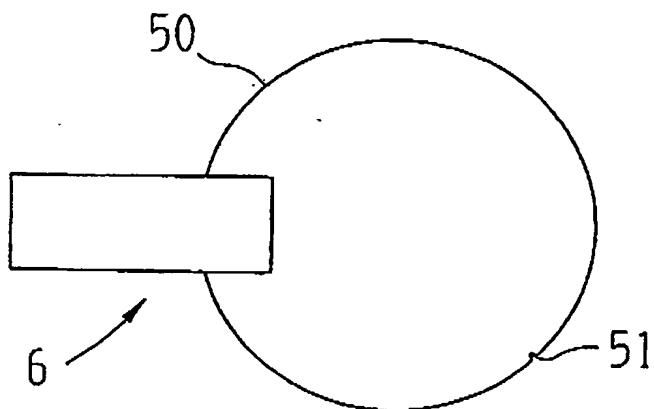


(b) Fig.3B



(図4)

(a) Fig. 4A



(b) Fig. 4B

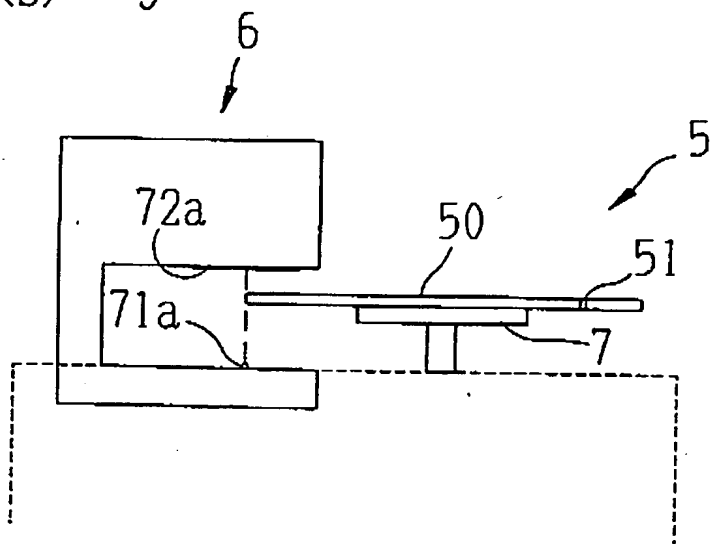


図5

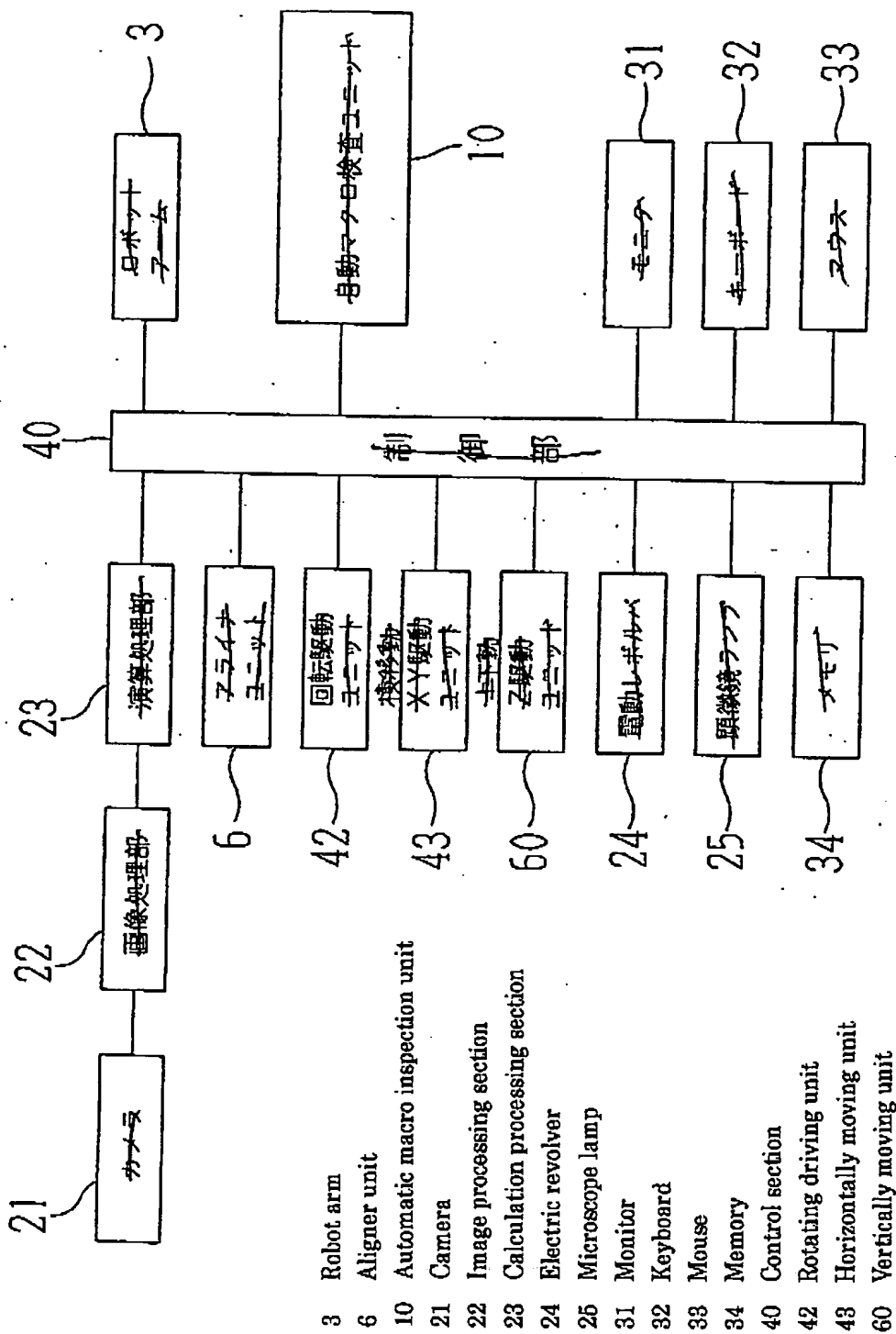


Fig.5

Start

S1 Input inspecting conditions (drawing stage, type number and manufacturing process).

S2 Start inspection.

55 Convey waler from carrier to mounting table with robot arm.

S4 Rotate mounting table.

55 Detect notch or orientation flat position and center position with aligner unit.

to adjust from one orientation flat position to predetermined position (direction) with rotating unit.

S1 Correct eccentricity of wafer with horizontally moving unit and move wafer to a predetermined inspecting position.

S8 Light microscope lamp at predetermined brightness.

allows the user to get magnification of objective lens at 2.5 times.

Move microscope unit in direction Z to adjust focus.

take photograph of water and process photographed image.

column and extract mask II image by pattern matching.

move valve with horizontally moving unit. (Position by inchings.)

Light microscope lamp at predetermined brightness.

two-wave electric revolver to 861 magnification of objective lens at 20 times.

Move microscope unit in direction Z to adjust focus.

Take photograph of mask ID and conduct image processing

confirm mask ID by pattern matching.

19 Does mask ID agree?

20 Convey water to automatic macro inspecting unit with robot arm.

21 Conduct inspection with automatic macro inspecting unit.

22 Return wafer to carrier with robot arm.

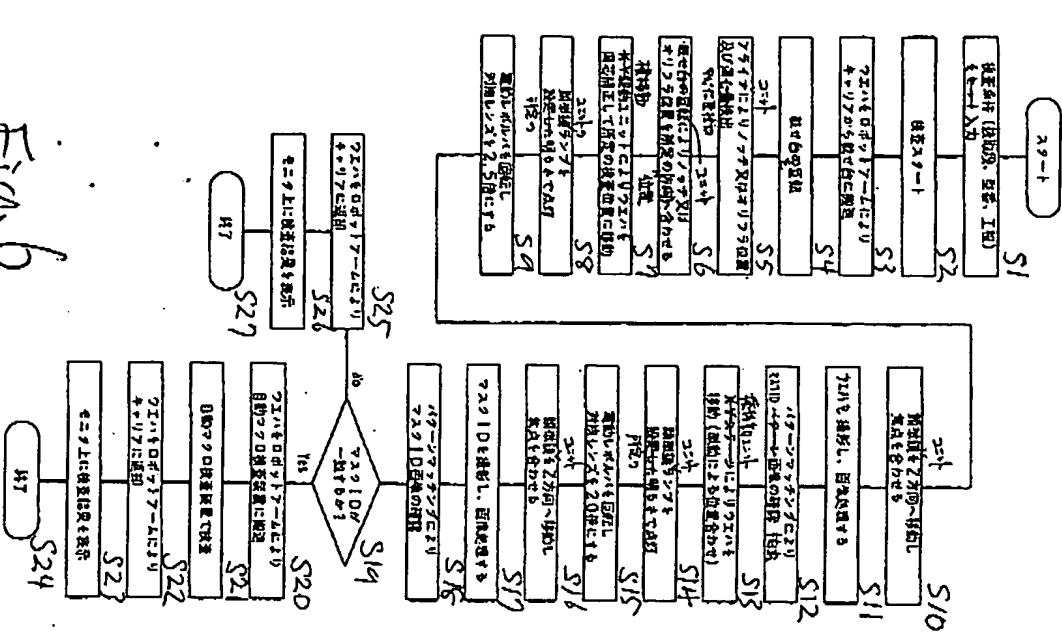
23 **Display result of inspection on monitor.**

24 End

20 Return water to carrier with robot arm.

26 **Display result of inspection on monitor.**

27 End



71. 5. 6

図7

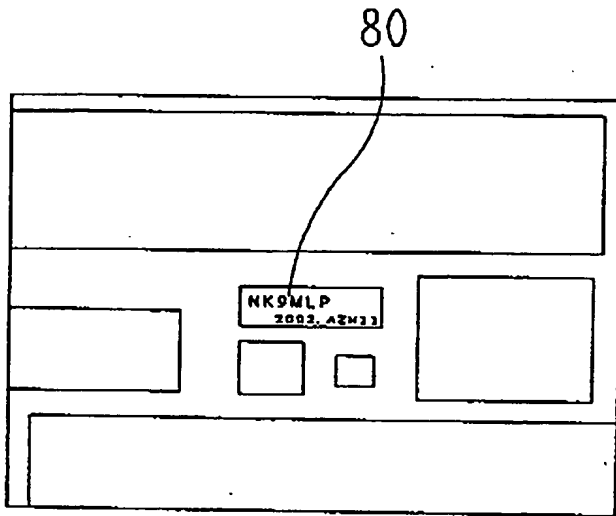


Fig. 7

図8

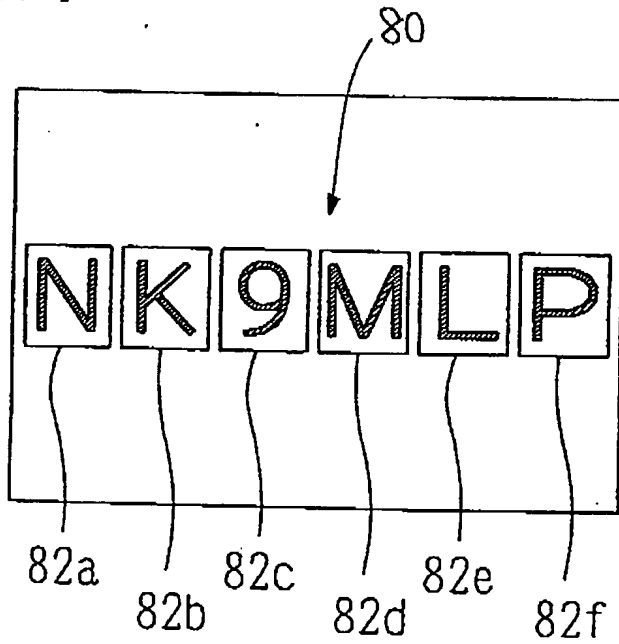


Fig. 8

【図9】

(a)

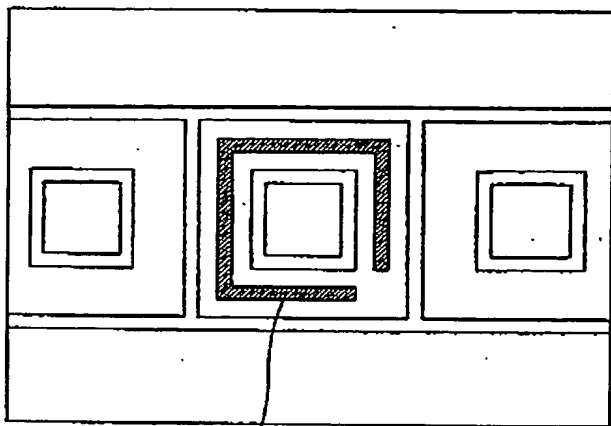


Fig. 9A

90

(b)

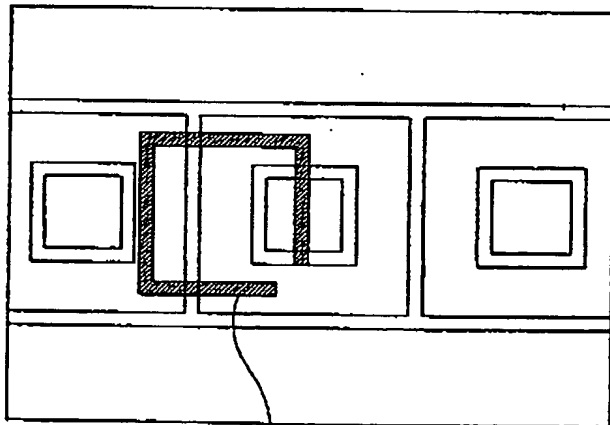


Fig. 9B

90